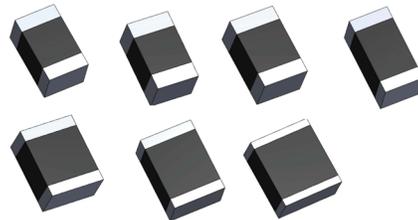


# AMLV

## Automotive grade multilayer varistor



### Product features

- AEC-Q200 qualified
- Seven compact footprint options: 0402 (1005 metric) , 0603 (1608 metric), 0805 (2012 metric), 1206 (3216 metric), 1210 (3225 metric), 1812 (4532 metric), 2220 (5750 metric)
- Working voltage: 5.5 Vdc to 56 Vdc  
4.0 Vac to 40 Vac
- Bi-directional
- Peak current (8/20  $\mu$ s) up to 1200 A
- Multilayer construction suited for high reliability automotive applications
- V-jump and load-dump protection
- Meets moisture sensitivity level (MSL): 1

### Applications

- Various automotive electrical control unit (ECU) applications
- Automotive bus systems (LIN, CAN, CAN-FD, FlexRay)
- Advanced driver assistance system (ADAS)
- In vehicle infotainment system (IVI)
- Seat motor circuit
- LED driver/ LED lamp
- Keyless entry
- Bluetooth
- Wiper motor
- Door control module

### Environmental compliance



### Ordering part number

**AMLV 04 V05 C033**

Family name

Package size

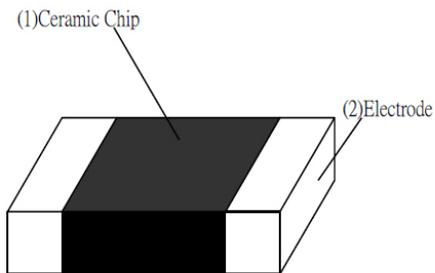
Working voltage (Vdc)

Capacitance code (pf)

**Product specifications**

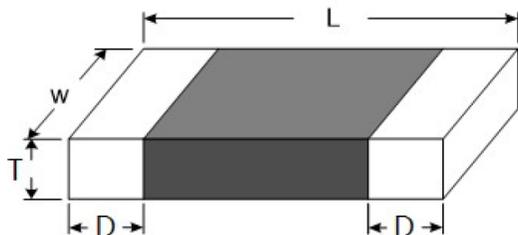
Part number	Working voltage		Varistor voltage @ 1 mAdc		Maximum clamping voltage 8/20 $\mu$ s (V)	Energy absorption 10/1000 $\mu$ s (J)	Peak current 8/20 $\mu$ s (A)	Typical capacitance @ 1 MHz (pF)	V <sub>jump</sub> (5 min) (V)	W <sub>LD</sub> (10x) (J)	Leakage current @ Vdc ( $\mu$ A)
	(Vdc)	(Vac)	(V min)	(V max)							
AMLV04V05C033	5.5	4	8.8	13.2	31 @ 1 A	0.02	4	33 @ 1 MHz	-	-	$\leq$ 20
AMLV04V05C090	5.5	4	8.8	13.2	30 @ 1 A	0.05	10	90 @ 1 MHz	-	-	$\leq$ 20
AMLV04V18C012	18	14	22	28	55 @ 1 A	0.03	2	12 @ 1 MHz	-	-	$\leq$ 20
AMLV04V18C040	18	14	22	28	50 @ 1 A	0.05	20	40 @ 1 MHz	-	-	$\leq$ 20
AMLV06V09C490	9	7	11	16	29 @ 1 A	0.1	30	490 @ 1 MHz	-	-	$\leq$ 20
AMLV06V18C012	18	14	23	30	55 @ 1 A	0.03	2	12 @ 1 MHz	-	-	$\leq$ 20
AMLV06V26C110	26	20	31	38	60 @ 1 A	0.1	30	110 @ 1 MHz	-	-	$\leq$ 20
AMLV06V32C010	32	25	51.9	70.1	120 @ 1 A	0.05	5	10 @ 1 MHz	-	-	$\leq$ 20
AMLV08V16C650	16	12	21.6	26.4	40 @ 1 A	0.3	120	650 @ 1 kHz	24.5	1	$\leq$ 20
AMLV08V18C650	18	14	23	28	44 @ 1 A	0.3	120	650 @ 1 kHz	24.5	1	$\leq$ 20
AMLV08V26C500	26	20	29.7	36.3	56 @ 1 A	0.3	80	500 @ 1 kHz	27	1	$\leq$ 20
AMLV08V31C250	31	25	35.1	42.9	67 @ 1 A	0.3	80	250 @ 1 kHz	29	0.5	$\leq$ 20
AMLV12V18C1000	18	14	22.95	28.05	42 @ 1 A	0.6	150	1000 @ 1 kHz	24.5	1.5	$\leq$ 20
AMLV12V26C800	26	20	29.7	36.3	54 @ 1 A	0.7	200	800 @ 1 kHz	27.5	1.2	$\leq$ 20
AMLV12V34C550	34	26	42.3	51.7	77 @ 1 A	0.4	200	550 @ 1 kHz	50	1.5	$\leq$ 20
AMLV12V48C270	48	37	55.8	68.2	100 @ 1 A	0.4	100	270 @ 1 kHz	59	1.2	$\leq$ 20
AMLV12V56C250	56	40	61.2	74.8	110 @ 1 A	0.5	100	250 @ 1 kHz	65	1.5	$\leq$ 20
AMLV13V18C3100	18	14	22.95	28.05	42 @ 2.5 A	1.6	500	3100 @ 1 kHz	27.5	3	$\leq$ 20
AMLV13V26C1500	26	20	29.7	36.3	54 @ 2.5 A	1.9	400	1500 @ 1 kHz	27	3	$\leq$ 20
AMLV13V31C1200	31	25	35.1	42.9	65 @ 2.5 A	1.7	300	1200 @ 1 kHz	29	3	$\leq$ 20
AMLV13V34C1100	34	26	42.3	51.7	75 @ 2.5 A	2.3	300	1100 @ 1 kHz	50	3	$\leq$ 20
AMLV13V45C600	45	35	50.4	61.6	90 @ 2.5 A	2.0	250	600 @ 1 kHz	60	1.5	$\leq$ 20
AMLV18V16C4500	16	12	21.6	26.4	40 @ 5 A	2.4	800	4500 @ 1 kHz	24.5	6	$\leq$ 20
AMLV18V26C3200	26	20	29.7	36.3	54 @ 5 A	3.0	800	3200 @ 1 kHz	30	6	$\leq$ 20
AMLV18V30C1700	30	23	35	43.0	77 @ 5 A	3.8	600	1700 @ 1 kHz	45	6	$\leq$ 20
AMLV22V16C20000	16	12	21.6	26.4	42 @ 10 A	10	1200	20000 @ 1 kHz	24.5	25	$\leq$ 20
AMLV22V34C6500	34	26	42.3	51.7	77 @ 10 A	12	1200	6500 @ 1 kHz	50	12	$\leq$ 20
AMLV22V38C3000	38	30	42.3	51.7	77 @ 10 A	12	1000	3000 @ 1 kHz	50	12	$\leq$ 20

**Construction**

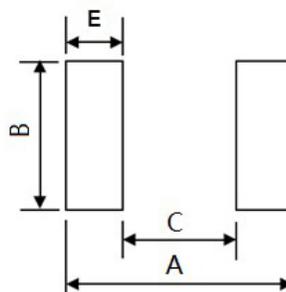


Component	Material
1. Ceramic chip	Metal oxides
2. Electrode	Ag-Ni-Sn

**Dimensions – mm**



**Pad layout**

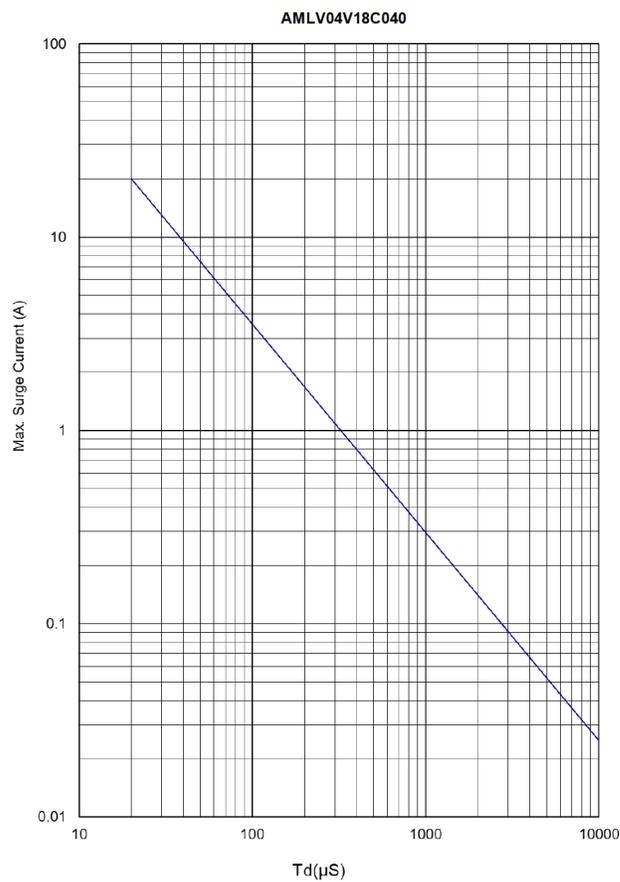
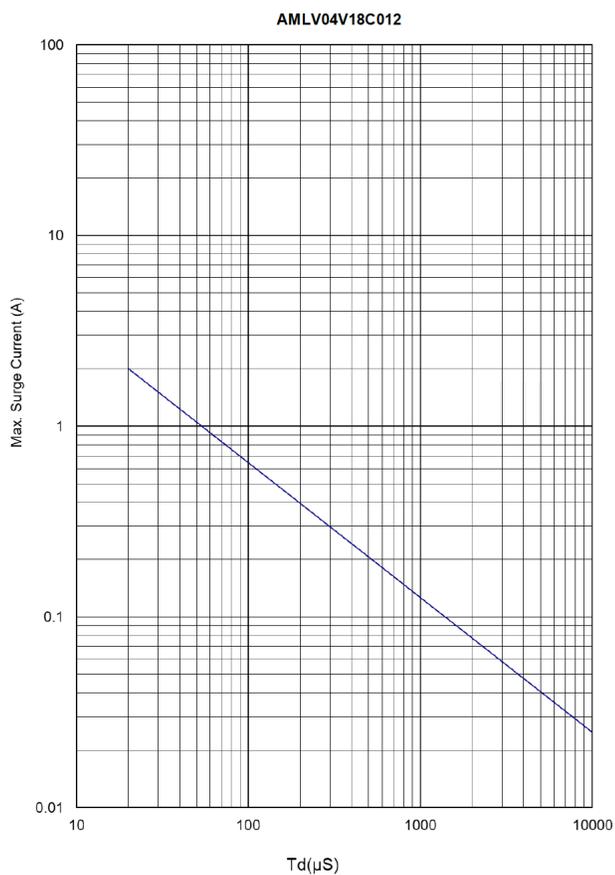
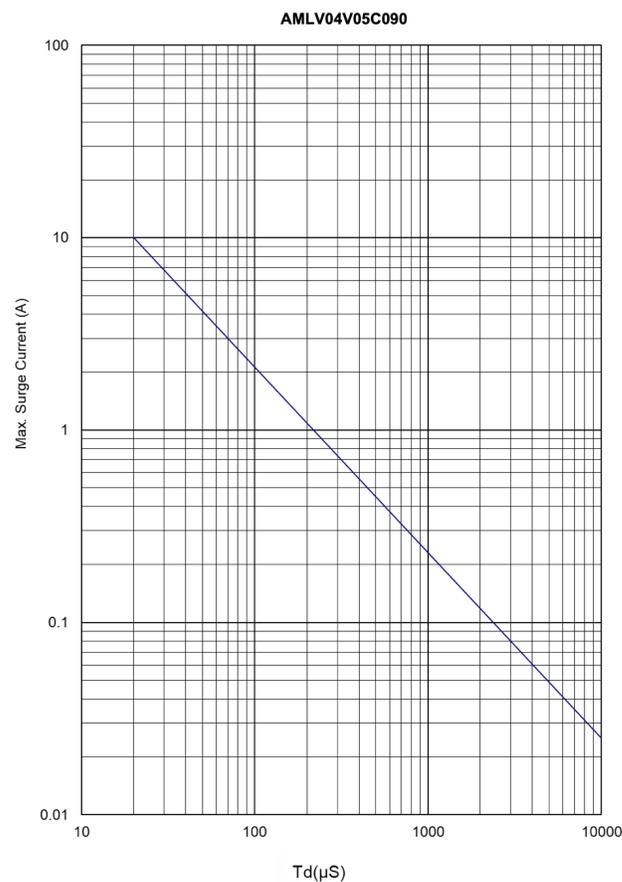
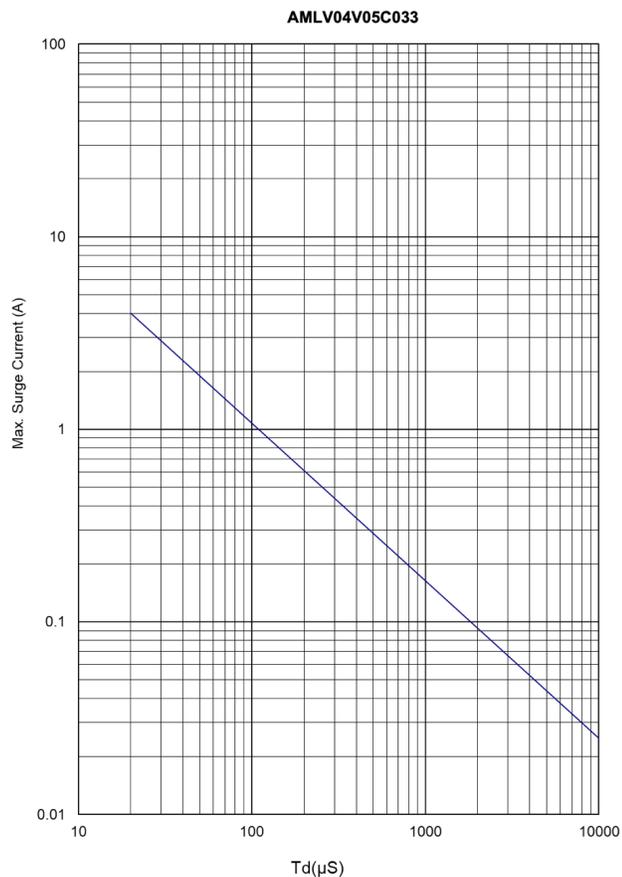


Part size	L	W	T (maximum)	D	A	B	C	E
AMLV04	1.00±0.15	0.50±0.10	0.6	0.20±0.10	1.7	0.6	0.5	0.6
AMLV06	1.60±0.15	0.80±0.15	0.95	0.35±0.15	2.8	1	0.8	1
AMLV08	2.00±0.20	1.25±0.20	1	0.40±0.20	3.4	1.4	1	1.2
AMLV12	3.20±0.30	1.60±0.20	1.5	0.50±0.20	4.5	1.8	2.1	1.2
AMLV13	3.20±0.30	2.50±0.25	1.5	0.50±0.20	4.5	2.8	2.1	1.2
AMLV18	4.50±0.40	3.20±0.30	2	0.60±0.30	6	3.6	3	1.5
AMLV22	5.70±0.40	5.00±0.30	2.5	0.60±0.30	7.2	5.5	4.2	1.5

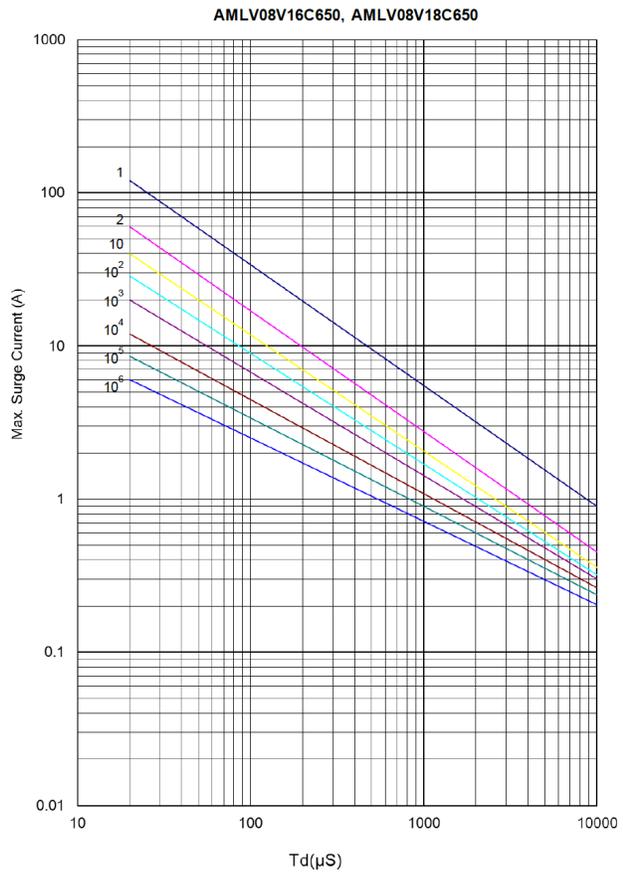
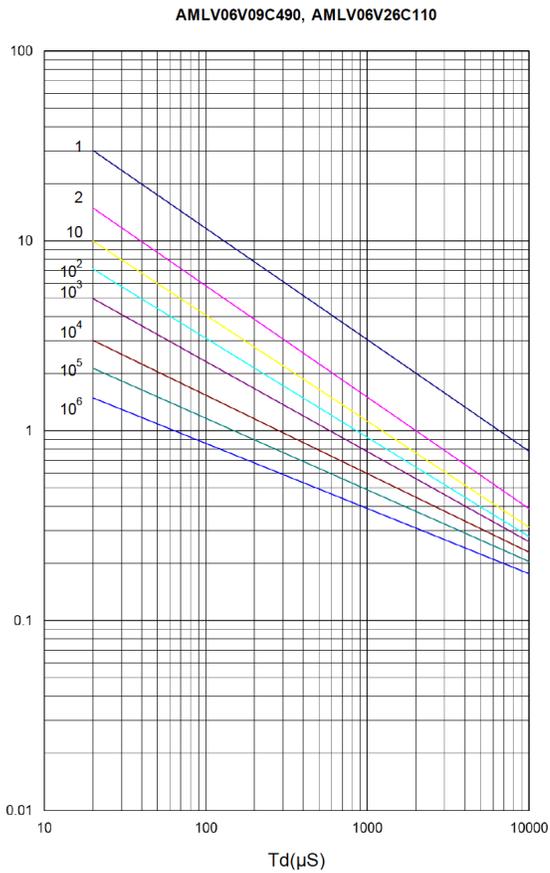
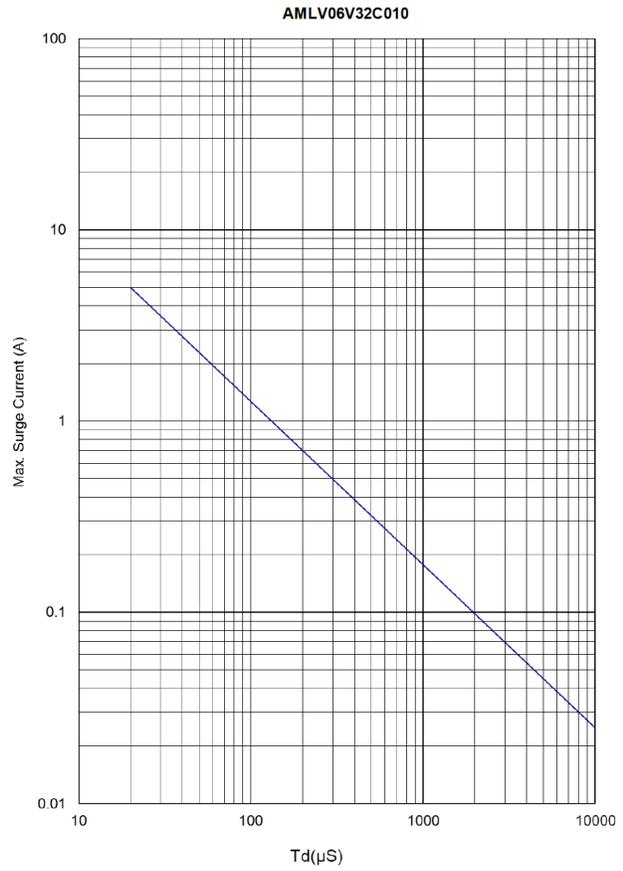
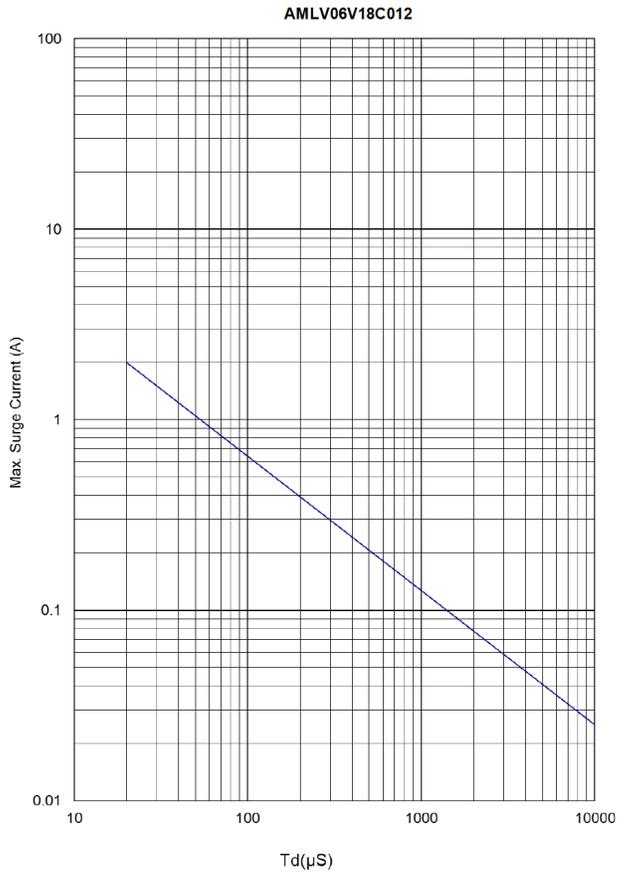
## General specifications

Operating temperature	- 55 °C to +125 °C (without derating)																																												
Storage temperature (component)	- 55 °C to +150 °C																																												
High temperature exposure	MIL-STD-202 Method 108, Temperature: +150 °C +3/-0 °C, Duration 1000 hours unpowered																																												
Temperature cycling	JESD22 Method JA-104, Temperature: -55 °C to +125 °C. Maximum transfer time 60 s, dwell time 30 min (air-air), Number of cycles: 1000 cycles																																												
	MIL-STD-202 Method 106, Duration of 1 cycle 24 hours, Number of cycles: 10 unpowered																																												
Moisture resistance	<table border="1"> <thead> <tr> <th rowspan="2">Step</th> <th colspan="2">Temp./ °C</th> <th>Humidity</th> <th>Period</th> </tr> <tr> <th>Start</th> <th>Finish</th> <th>%</th> <th>hr</th> </tr> </thead> <tbody> <tr> <td>1</td> <td>25</td> <td>65</td> <td>90-100</td> <td>2.5</td> </tr> <tr> <td>2</td> <td>65</td> <td>65</td> <td>90-100</td> <td>3.0</td> </tr> <tr> <td>3</td> <td>65</td> <td>25</td> <td>80-100</td> <td>2.5</td> </tr> <tr> <td>4</td> <td>25</td> <td>65</td> <td>90-100</td> <td>2.5</td> </tr> <tr> <td>5</td> <td>65</td> <td>65</td> <td>90-100</td> <td>3.0</td> </tr> <tr> <td>6</td> <td>65</td> <td>25</td> <td>80-100</td> <td>2.5</td> </tr> <tr> <td>7</td> <td>25</td> <td>25</td> <td>80-100</td> <td>8.0</td> </tr> </tbody> </table>	Step	Temp./ °C		Humidity	Period	Start	Finish	%	hr	1	25	65	90-100	2.5	2	65	65	90-100	3.0	3	65	25	80-100	2.5	4	25	65	90-100	2.5	5	65	65	90-100	3.0	6	65	25	80-100	2.5	7	25	25	80-100	8.0
Step	Temp./ °C		Humidity	Period																																									
	Start	Finish	%	hr																																									
1	25	65	90-100	2.5																																									
2	65	65	90-100	3.0																																									
3	65	25	80-100	2.5																																									
4	25	65	90-100	2.5																																									
5	65	65	90-100	3.0																																									
6	65	25	80-100	2.5																																									
7	25	25	80-100	8.0																																									
Biased humidity	MIL-STD-202 Method 103, Temperature: +85 °C, Humidity: 85%, Duration: 1000 hours, Bias at working voltage Vdc																																												
Operational life	MIL-STD-202 Method 108, Temperature: +125 °C, Duration: 1000 hours, Bias at working voltage Vdc																																												
Resistance to solvent	MIL-STD-202 Method 215, Solvent 1: 1 part (by volume) of isopropyl alcohol, 3 parts (by volume) of mineral spirits																																												
Mechanical shock	MIL-STD-202 Method 213, Test condition F Peak value: 1500 g's, Half sin waveform, normal duration 0.5 ms, In 3 directions perpendicularly intersecting each other (total 18 times)																																												
Vibration	MIL-STD-202 Method 204, Acceleration: 5 g's Sweep time: 20 minutes, Frequency range: 10 to 2000 Hz, 3 x 12 cycles																																												
Resistance to soldering heat	MIL-STD-202 Method 210, Condition B, no pre-heat of samples. Temperature: +260 ± 5 °C, time: 10 ± 1 s. Immersion and emersion rate: 25 mm/s ± 6 mm/s, 1 cycle																																												
Thermal shock	MIL-STD-202 Method 107, Temperature: -55 °C + 0/-3 °C to +125 °C + 3/-0 °C max., transfer time: 20 s, Dwell time: 15 minutes, air to air Number of cycles: 300 cycles																																												
ESD	AEC-Q200-002, Discharge capacitance: 150 pF Charging voltage: 30 kV min, Contact discharge, 1 pulse each polarity																																												
Solderability	IEC60068-2-58, J-STD-002, a) 4 hours @ +155 °C dry heat, dip @ +245 ± 5 °C, 3 ± 0.3 s b) Steam aging 8 hours ± 15 minutes @ +93 ± 3 °C, dip @ +260 ± 5 °C, 7 ± 0.5 s, 95% of termination wetted																																												
Board flex	AEC-Q200-005, Bend the board: 2 mm (min.), Duration of the applied forces: 60 + 5/-0 S No visible damage																																												
Electrical transient conduction	ISO7637-2, Test pulses 5a																																												

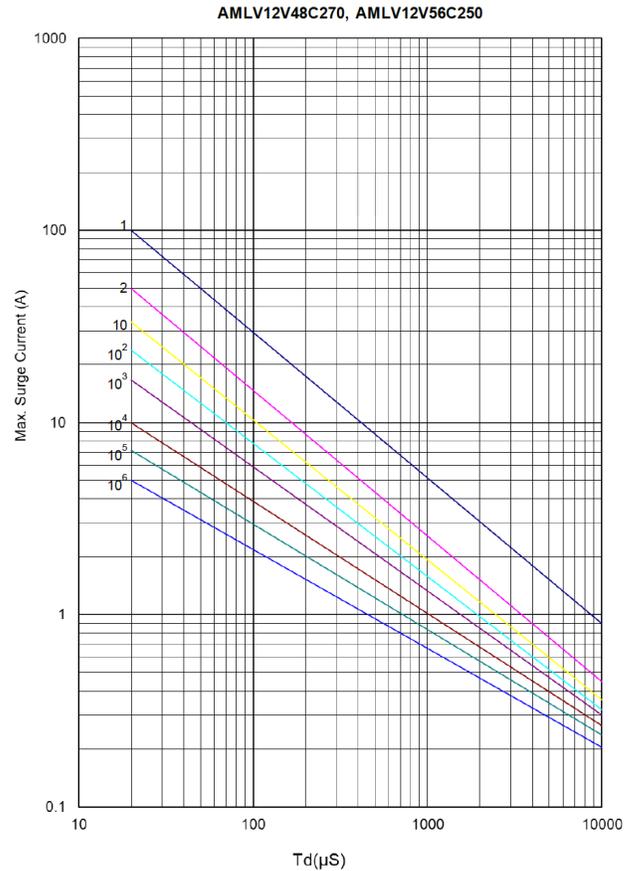
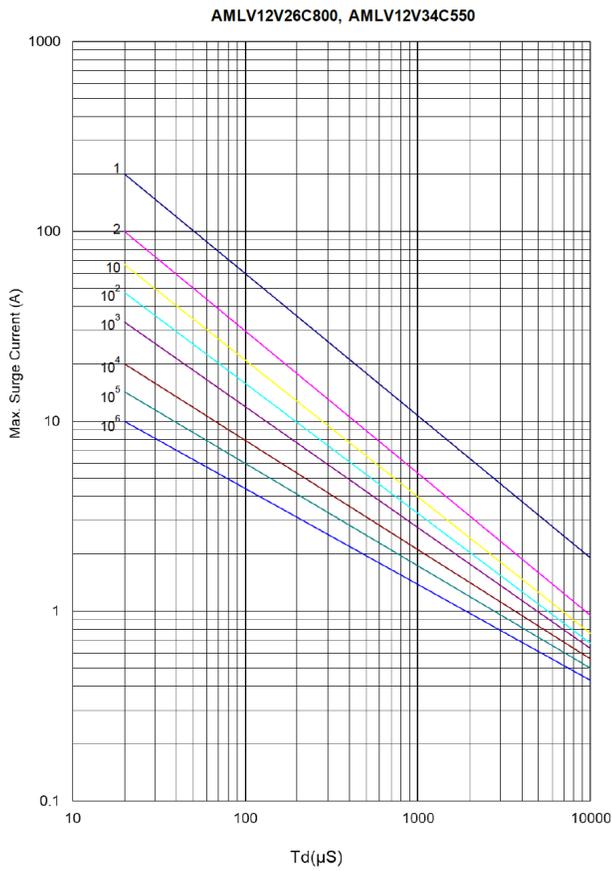
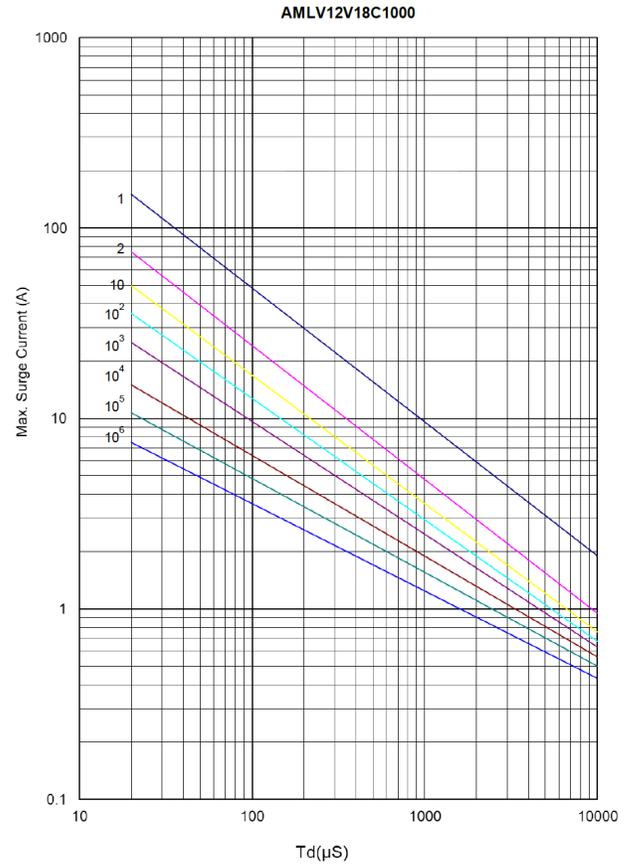
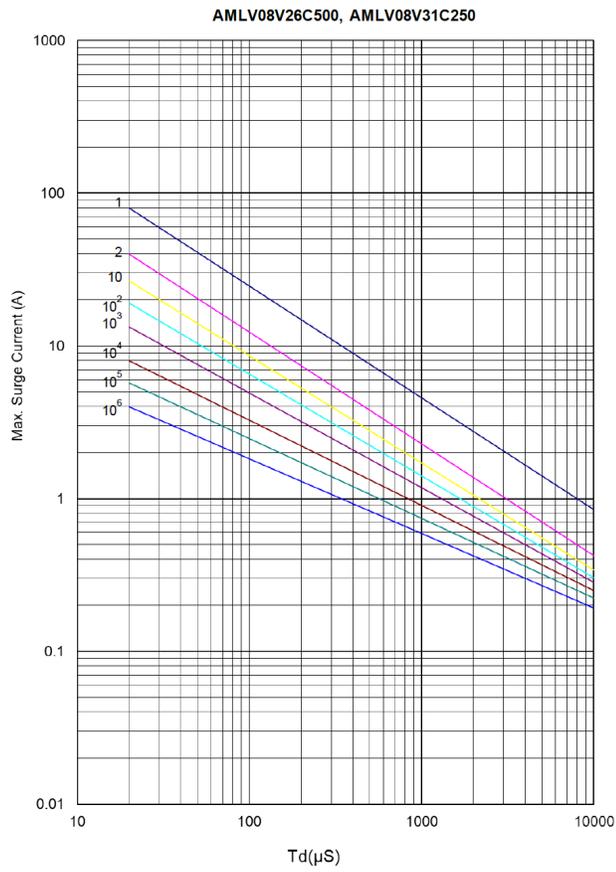
Maximum surge current derating curves



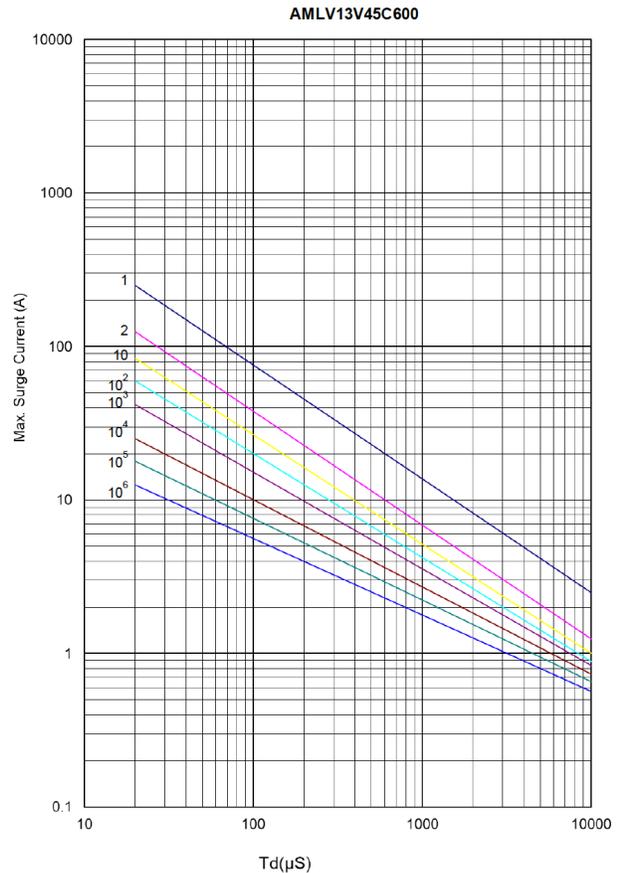
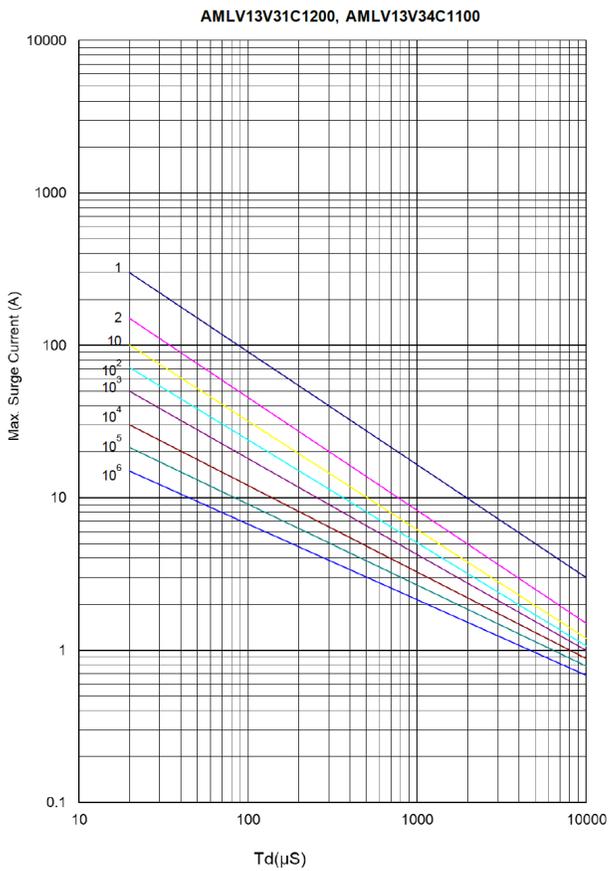
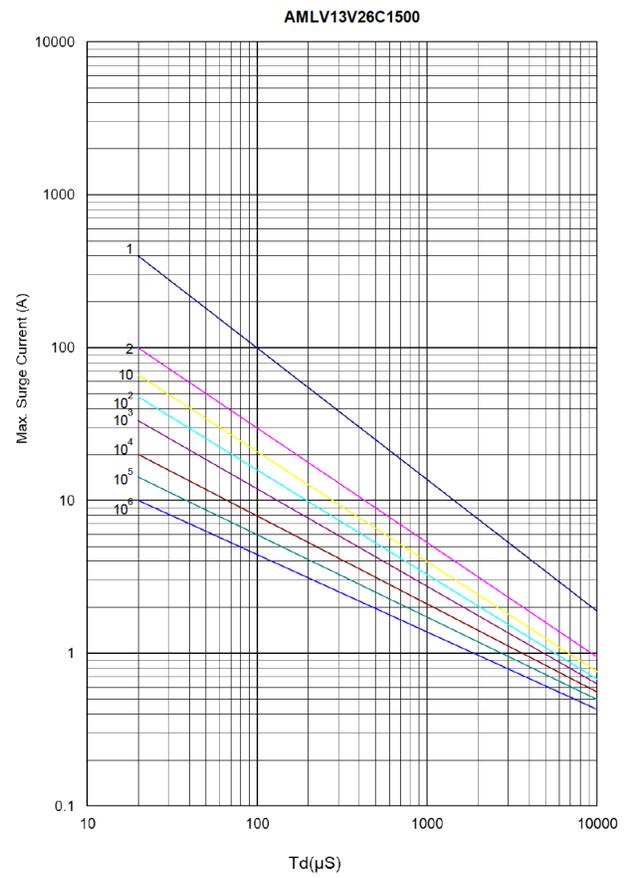
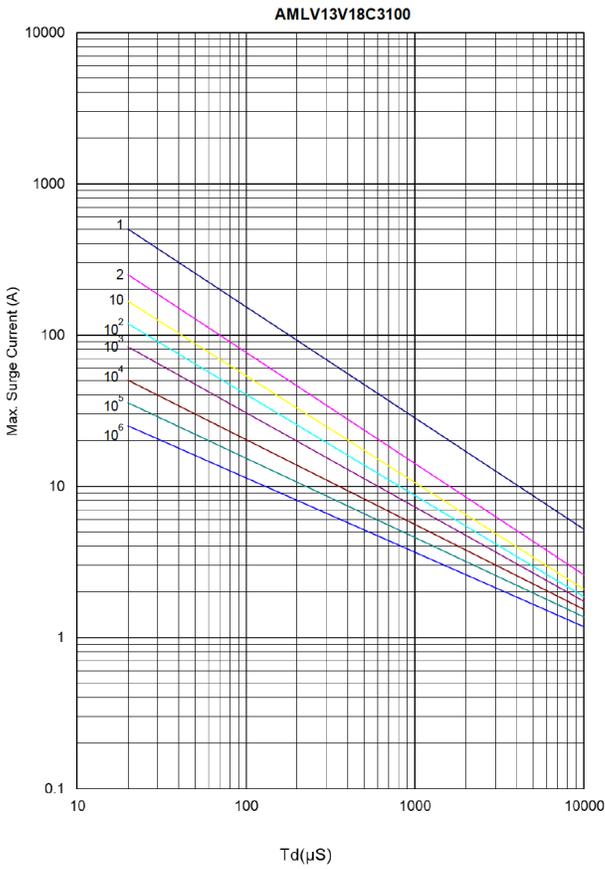
Maximum surge current derating curves



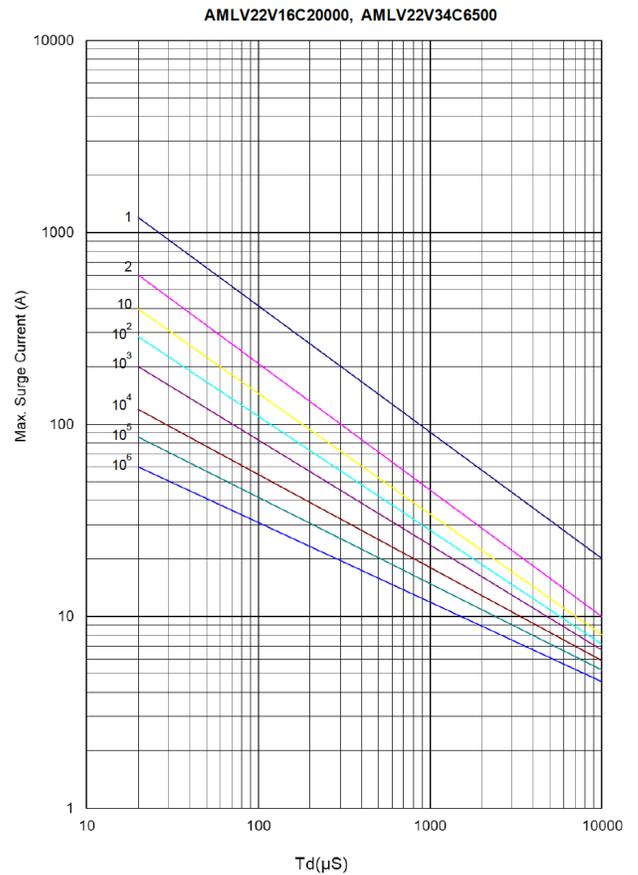
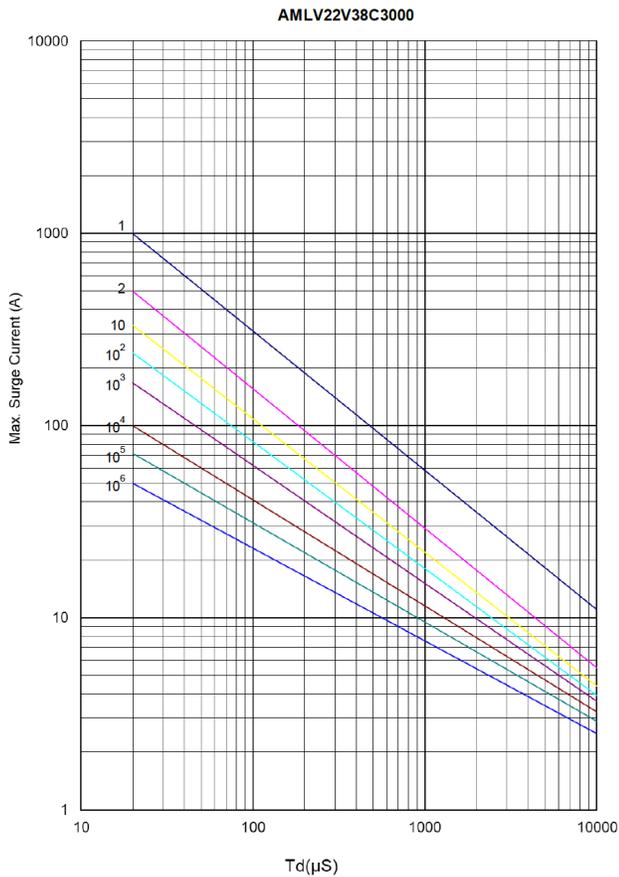
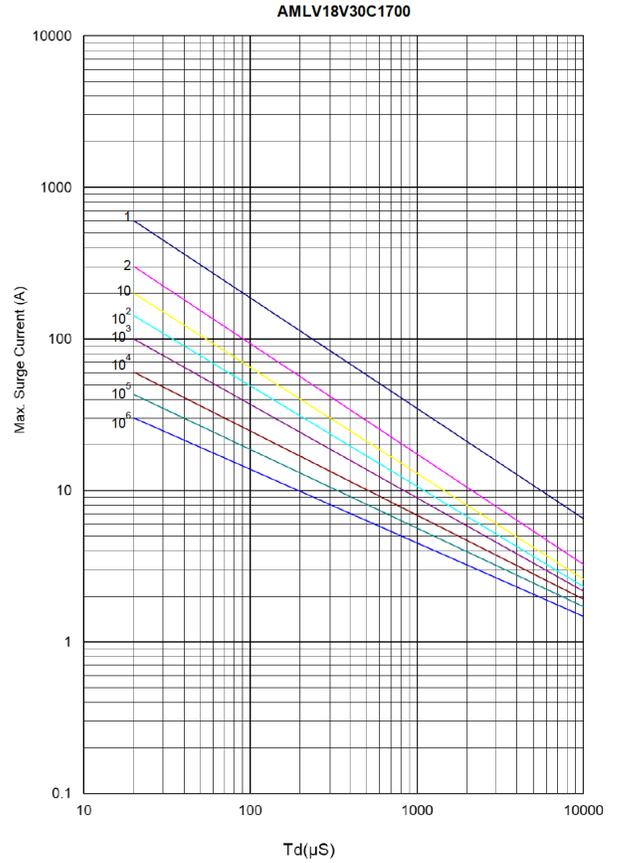
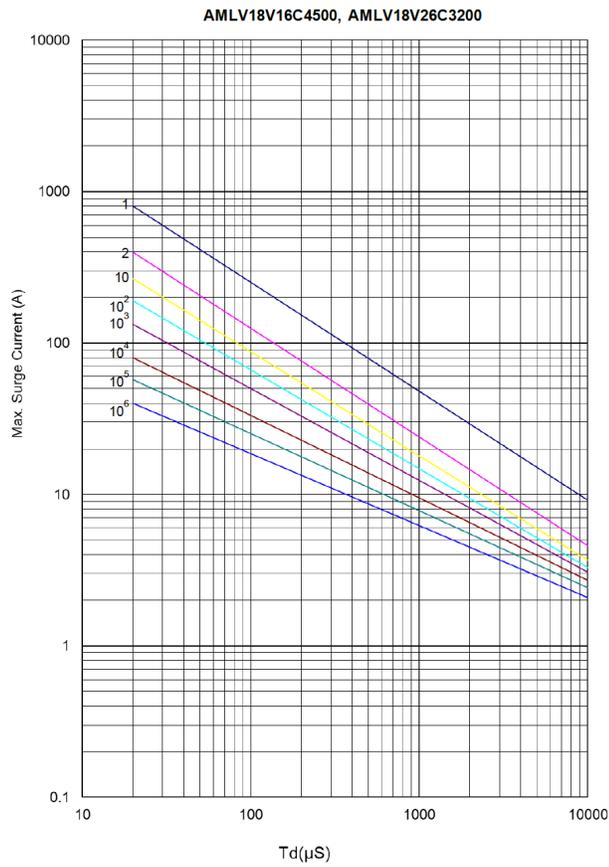
Maximum surge current derating curves



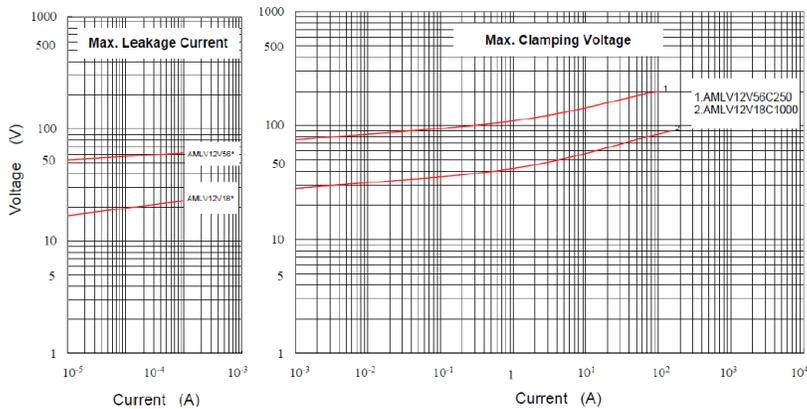
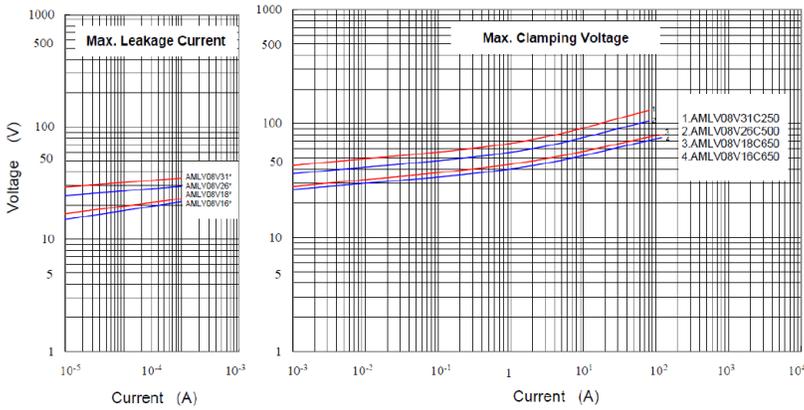
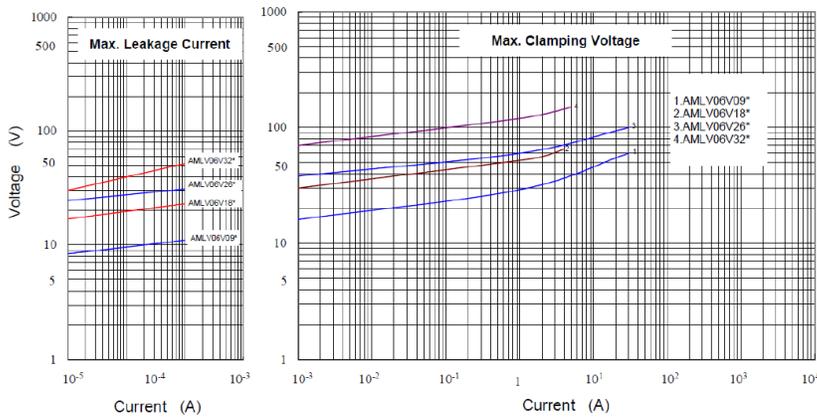
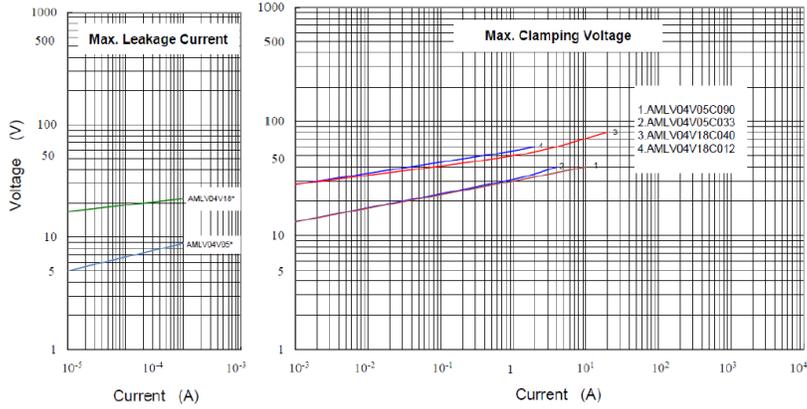
Maximum surge current derating curves



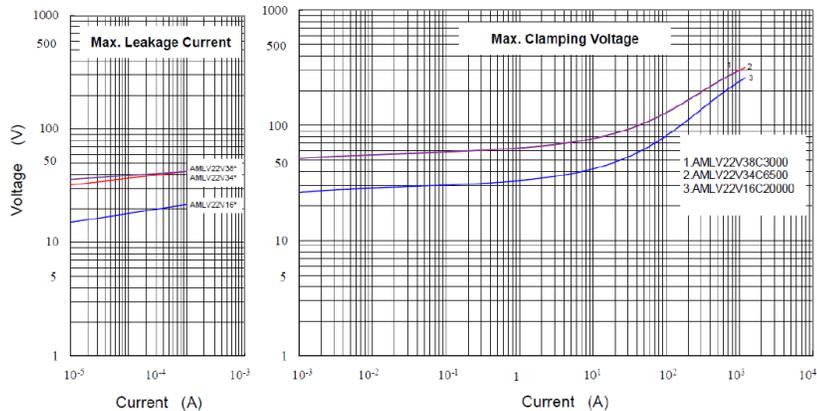
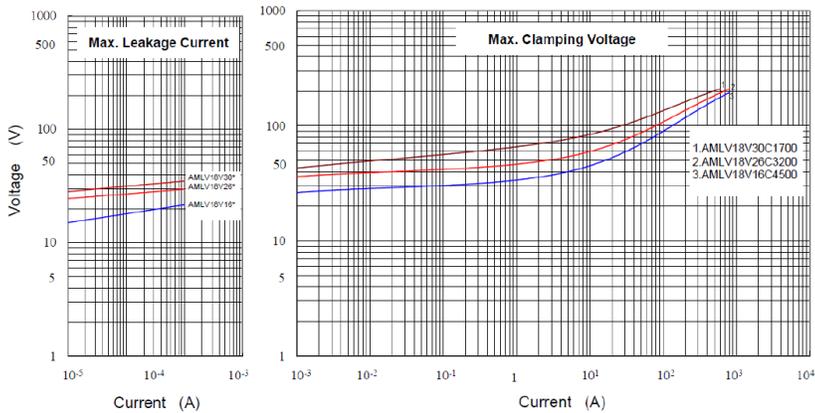
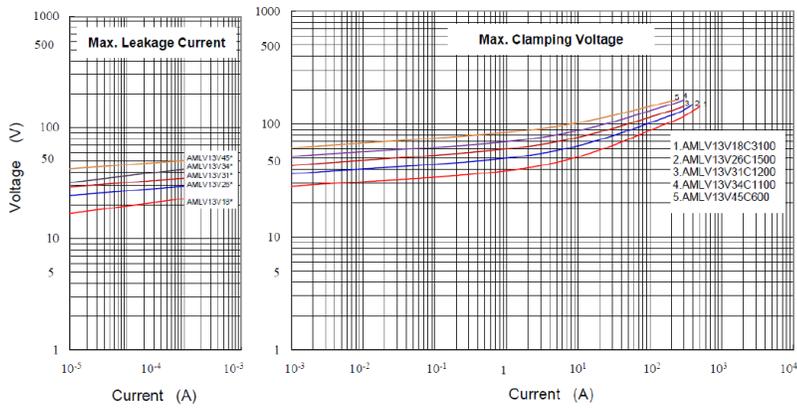
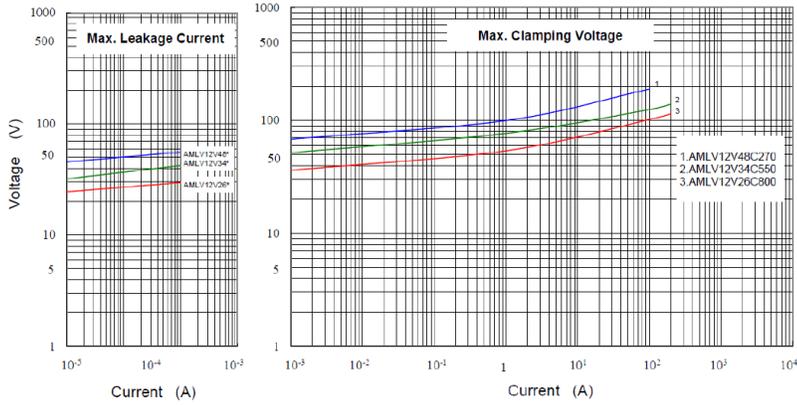
Maximum surge current derating curves



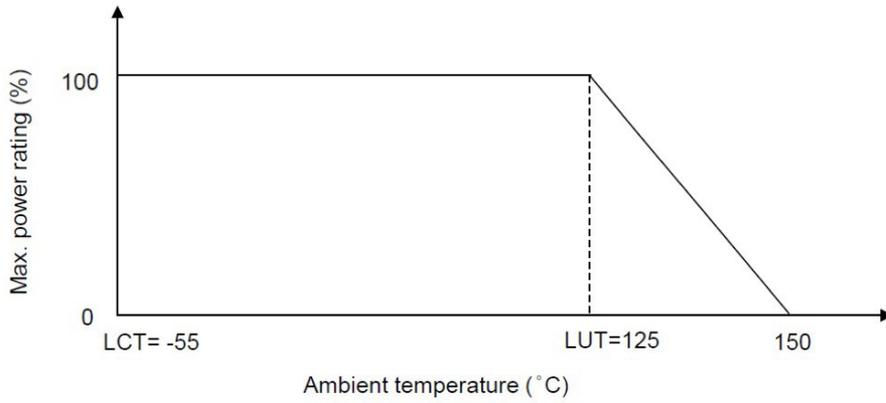
Maximum leakage current and maximum clamping voltage curves



Maximum leakage current and maximum clamping voltage curves

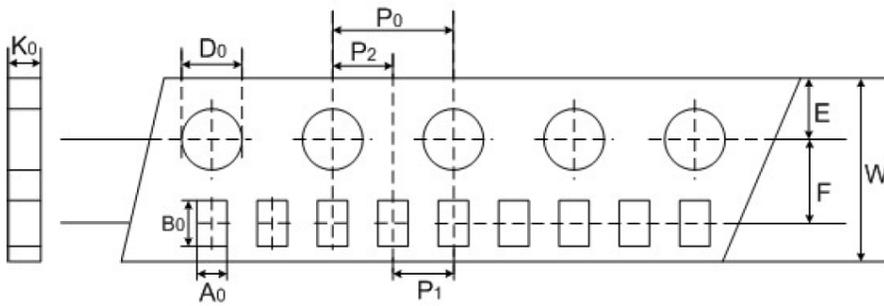


**Power derating curve**



**Packaging information - mm**

AMLV04: 10,000 parts on a 7" diameter tape and reel (EIA-481 compliant)

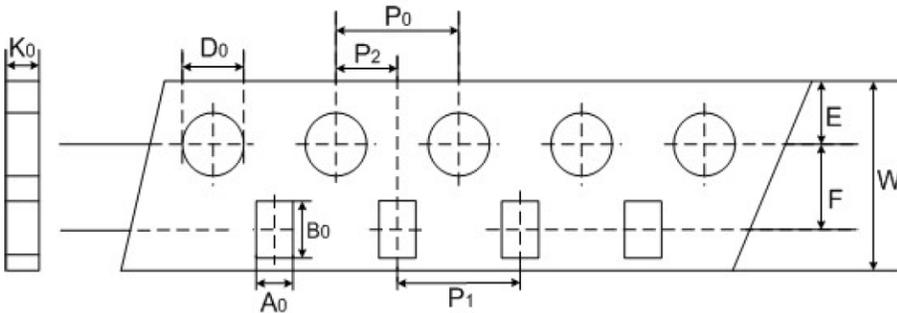


Dimension	AMLV04
A0	0.62 ± 0.05
B0	1.12 ± 0.12
W	8 ± 0.2
E	1.75 ± 0.1
F	3.5 ± 0.05
P0	4 ± 0.1
P1	2 ± 0.1
P2	2 ± 0.05
D0	1.55 ± 0.1
K0	0.60 ± 0.1

**Packaging information - mm**

AMLV06: 4,000 parts on a 7" diameter tape and reel (EIA-481 compliant)

AMLV08: 3,500 parts on a 7" diameter tape and reel (EIA-481 compliant)

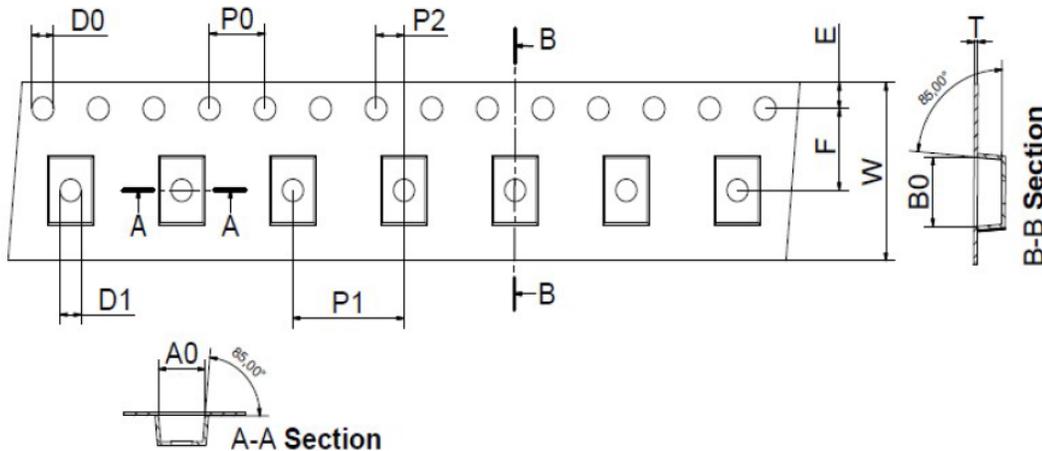


Dimension	AMLV06	AMLV08
A0	1.1 ± 0.2	1.5 ± 0.2
B0	1.9 ± 0.2	2.3 ± 0.2
W	8 ± 0.2	8 ± 0.2
E	1.75 ± 0.1	1.75 ± 0.1
F	3.5 ± 0.05	3.5 ± 0.05
P0	4 ± 0.1	4 ± 0.1
P1	4 ± 0.1	4 ± 0.1
P2	2 ± 0.05	2 ± 0.05
D0	1.55 ± 0.1	1.55 ± 0.1
K0	0.95 ± 0.1	1.00 ± 0.1

AMLV12 and AMLV13: 2500 parts on a 7" diameter tape and reel (EIA-481 compliant)

AMLV18: 1000 part on a 7" diameter tape and reel (EIA-481 compliant)

AMLV22: 800 part on a 7" diameter tape and reel (EIA-481 compliant)



Dimension	AMLV12	AMLV13	AMLV18	AMLV22
A0	1.85 ± 0.2	2.75 ± 0.2	3.65 ± 0.2	5.50 ± 0.2
B0	3.45 ± 0.2	3.55 ± 0.2	4.96 ± 0.2	6.25 ± 0.2
W	8 ± 0.2	8 ± 0.2	12 ± 0.3	12 ± 0.3
E	1.75 ± 0.1	1.75 ± 0.1	1.75 ± 0.1	1.75 ± 0.1
F	3.5 ± 0.05	3.5 ± 0.05	5.5 ± 0.05	5.5 ± 0.05
P0	4 ± 0.1	4 ± 0.1	4 ± 0.1	4 ± 0.1
P1	4 ± 0.1	4 ± 0.1	8 ± 0.1	8 ± 0.1
P2	2 ± 0.05	2 ± 0.05	2 ± 0.05	2 ± 0.05
D0	1.55 ± 0.1	1.55 ± 0.1	1.55 ± 0.1	1.55 ± 0.1
D1	1.00 ± 0.1	1.00 ± 0.1	1.50 ± 0.1	1.50 ± 0.1
T	0.25 ± 0.1	0.25 ± 0.1	0.25 ± 0.1	0.25 ± 0.1

Solder reflow profile

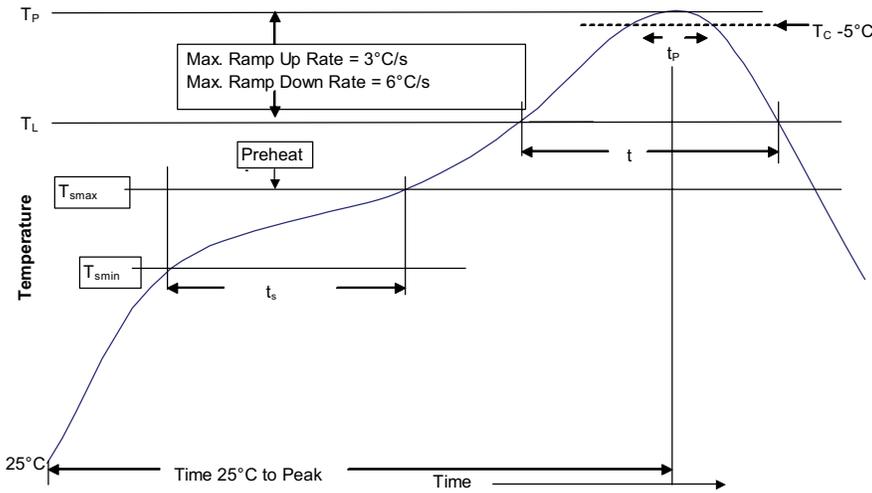


Table 1 - Standard SnPb solder (T<sub>C</sub>)

Package thickness	Volume mm <sup>3</sup> <350	Volume mm <sup>3</sup> ≥350
<2.5 mm)	235 °C	220 °C
≥2.5 mm	220 °C	220 °C

Table 2 - Lead (Pb) Free Solder (T<sub>C</sub>)

Package thickness	Volume mm <sup>3</sup> <350	Volume mm <sup>3</sup> 350 - 2000	Volume mm <sup>3</sup> >2000
<1.6 mm	260 °C	260 °C	260 °C
1.6 – 2.5 mm	260 °C	250 °C	245 °C
>2.5 mm	250 °C	245 °C	245 °C

Reference JDEC J-STD-020

Profile feature	Standard SnPb solder	Lead (Pb) free solder
Preheat and soak		
• Temperature min. (T <sub>Smin</sub> )	100 °C	150 °C
• Temperature max. (T <sub>Smax</sub> )	150 °C	200 °C
• Time (T <sub>Smin</sub> to T <sub>Smax</sub> ) (t <sub>s</sub> )	60-120 seconds	60-120 seconds
Average ramp up rate T <sub>Smax</sub> to T <sub>p</sub>	3 °C/ second max.	3 °C/ second max.
Liquidous temperature (T <sub>L</sub> )	183 °C	217 °C
Time at liquidous (t <sub>L</sub> )	60-150 seconds	60-150 seconds
Peak package body temperature (T <sub>p</sub> )*	Table 1	Table 2
Time (t <sub>p</sub> )** within 5 °C of the specified classification temperature (T <sub>C</sub> )	20 seconds**	30 seconds**
Average ramp-down rate (T <sub>p</sub> to T <sub>Smax</sub> )	6 °C/ second max.	6 °C/ second max.
Time 25 °C to peak temperature	6 minutes max.	8 minutes max.

\* Tolerance for peak profile temperature (T<sub>p</sub>) is defined as a supplier minimum and a user maximum.

\*\* Tolerance for time at peak profile temperature (t<sub>p</sub>) is defined as a supplier minimum and a user maximum.

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